SVENSK STANDARD SS-EN IEC 61188-6-1

Fastställd	Utgåva	Sida	Ansvarig kommitté
2021-06-16	1	1 (1+32)	SEK Elektro-tekniska rådet

Konstruktion och användning av mönsterkort och kretskort – Del 6-1: Utformning av anslutningsytor – Allmänna fordringar på anslutningsytor på mönsterkort

Circuit boards and circuit board assemblies – Design and use – Part 6-1: Land pattern design – Generic requirements for land pattern on circuit boards

Som svensk standard gäller europastandarden EN IEC 61188-6-1:2021. Den svenska standarden innehåller den officiella engelska språkversionen av EN IEC 61188-6-1:2021.

Nationellt förord

Europastandarden EN IEC 61188-6-1:2021

består av:

– **europastandardens ikraftsättningsdokument,** utarbetat inom CENELEC
– **IEC 61188-6-1, First edition, 2021 - Circuit boards and circuit board assemblies - Design and use - Part 6-1: Land pattern design - Generic requirements for land pattern on circuit boards**

utarbetad inom International Electrotechnical Commission, IEC.

Tidigare fastställd svensk standard SS-EN 61188-5-1, utgåva 1, 2003, gäller ej fr o m 2024-03-30.

ICS 31.180.00; 31.190.00

Denna standard är fastställd av SEK Svensk Elstandard,
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Standarder underlättar utvecklingen och höjer elsäkerheten

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 61188-6-1

April 2021

ICS 31.180; 31.190

Supersedes EN 61188-5-1:2002 and all of its amendments and corrigenda (if any)

English Version

Circuit boards and circuit board assemblies - Design and use - Part 6-1: Land pattern design - Generic requirements for land pattern on circuit boards (IEC 61188-6-1:2021)

Cartes imprimées et cartes imprimées équipées - Conception et utilisation - Partie 6-1: Conception de la zone de report - Exigences génériques pour la zone de report sur les cartes imprimées (IEC 61188-6-1:2021)

Leiterplatten und Flachbaugruppen - Konstruktion und Anwendung - Teil 6-1: Anschlussflächengestaltung - Allgemeine Anforderungen an die Anschlussflächenstruktur auf Leiterplatten (IEC 61188-6-1:2021)

This European Standard was approved by CENELEC on 2021-03-30. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Republic of North Macedonia, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

Ref. No. EN IEC 61188-6-1:2021 E

SEK Svensk Elstandard

SS-EN IEC 61188-6-1, utg 1:2021

European foreword

The text of document 91/1636/CDV, future edition 1 of IEC 61188-6-1, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61188-6-1:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-12-30
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-03-30

This document supersedes EN 61188-5-1:2002 and all of its amendments and corrigenda (if any).

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 61188-6-1:2021 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61188-5-1:2002	NOTE	Harmonized as EN 61188-5-1:2002 (not modified)
IEC 61188-5-2:2003	NOTE	Harmonized as EN 61188-5-2:2003 (not modified)
IEC 61188-5-3:2007	NOTE	Harmonized as EN 61188-5-3:2007 (not modified)
IEC 61188-5-4:2007	NOTE	Harmonized as EN 61188-5-4:2007 (not modified)
IEC 61188-5-5:2007	NOTE	Harmonized as EN 61188-5-5:2007 (not modified)
IEC 61188-5-6:2003	NOTE	Harmonized as EN 61188-5-6:2003 (not modified)
IEC 61188-5-8:2007	NOTE	Harmonized as EN 61188-5-8:2008 (not modified)
IEC 61188-6-2	NOTE	Harmonized as EN IEC 61188-6-2
IEC 61760-1	NOTE	Harmonized as EN IEC 61760-1

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-
IEC 61191-1	-	Printed board assemblies - Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN IEC 61191-1	-
IEC 61191-2	2017	Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies	EN 61191-2	2017
IEC 61191-3	-	Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assemblies	EN 61191-3	-
IEC 61191-4	-	Printed board assemblies - Part 4: Sectional specification - Requirements for terminal soldered assemblies	EN 61191-4	-
IEC 61760-3	-	Surface mounting technology - Part 3: Standard method for the specification of components for through-hole reflow (THR) soldering	EN IEC 61760-3	-

CONTENTS

INTERNATIONAL ELECTROTECHNICAL COMMISSION

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CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES – DESIGN AND USE –

Part 6-1: Land pattern design – Generic requirements for land pattern on circuit boards

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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IEC 61188-6-1 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

This first edition cancels and replaces the first edition of IEC 61188-5-1 published in 2002, and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) The content is completely updated to reflect current industry requirements. See Introduction.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1636/CDV	91/1671/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61188 series, published under the general title *Circuit boards and circuit board assemblies – Design and use*, can be found on the IEC website.

Future documents in this series will carry the new general title as cited above. Titles of existing documents in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The "colour inside" logo on the cover page of this document indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

Explanation why the following standards will be replaced by the new IEC 6188-6 series:

IEC 61188-5-1:2002, *Printed boards and printed board assemblies – Design and use – Part 5-1: Attachment (land/joint) considerations – Generic requirements*

IEC 61188-5-2:2003, *Printed boards and printed board assemblies – Design and use – Part 5-2: Attachment (land/joint) considerations – Discrete components*

IEC 61188-5-3:2007, *Printed boards and printed board assemblies – Design and use – Part 5-3: Attachment (land/joint) considerations – Components with gull-wing leads on two sides*

IEC 61188-5-4:2007, *Printed boards and printed board assemblies – Design and use – Part 5-4: Attachment (land/joint) considerations – Components with J leads on two sides*

IEC 61188-5-5:2007, *Printed boards and printed board assemblies – Design and use – Part 5-5: Attachment (land/joint) considerations – Components with gull-wing leads on four sides*

IEC 61188-5-6:2003, *Printed boards and printed board assemblies – Design and use – Part 5-6: Attachment (land/joint) considerations – Chip carriers with J-leads on four sides*

IEC 61188-5-8:2007, *Printed board and printed board assemblies – Design and use – Part 5-8: Attachment (land/joint) considerations – Area array components (BGA, FBGA, CGA, LGA)*

Content is mostly equivalent to IPC-782A with Amendments 1 and 2, which was replaced in 2002 by IPC-7351. The component spectrum and pitch levels have dramatically increased since publication of the IEC 61188-5 (all parts) and the dimensioning concept does no longer fulfil the mounting and soldering requirements.

CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES – DESIGN AND USE –

Part 6-1: Land pattern design – Generic requirements for land pattern on circuit boards

1 Scope

This part of IEC 61188 specifies the requirements for soldering surfaces on circuit boards. This includes lands and land pattern for surface mounted components and also solderable hole configurations for through-hole mounted components. These requirements are based on the solder joint requirements of the IEC 61191-1, IEC 61191-2, IEC 61191-3 and IEC 61191-4.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61191-1, *Printed board assemblies – Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies*

IEC 61191-2:2017, *Printed board assemblies – Part 2: Sectional specification – Requirements for surface mount soldered assemblies*

IEC 61191-3, *Printed board assemblies – Part 3: Sectional specification – Requirements for through-hole mount soldered assemblies*

IEC 61191-4, *Printed board assemblies – Part 4: Sectional specification – Requirements for terminal soldered assemblies*

IEC 61760-3, *Surface mounting technology – Part 3: Standard method for the specification of components for through hole reflow (THR) soldering*